

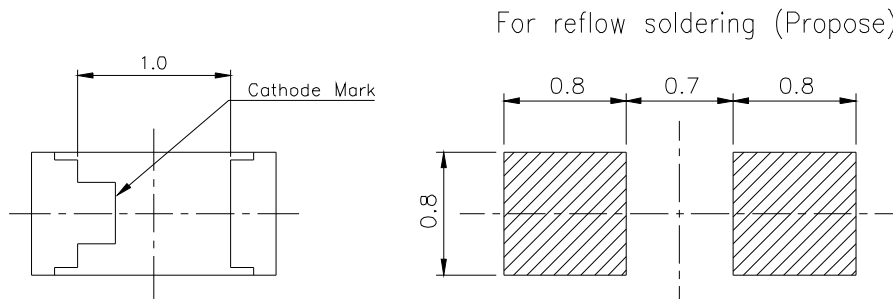
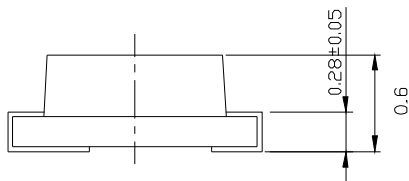
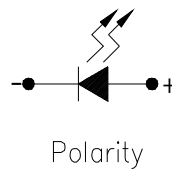
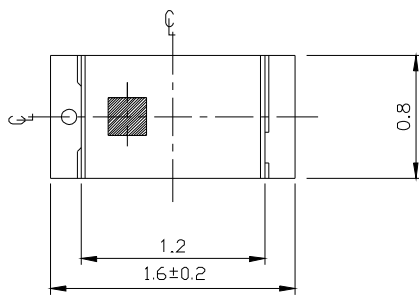
Features

- Fit automatic placement equipment.
- Fit Compatible with infrared and vapor phase reflow solder process.
- Pb-free.
- RoHS compliant.

Descriptions

- For higher packing density .
- For minature applications .
- Yellow Diffused Lens
- Chip material : InGaN .
- Emitting color : White.

Package Outline Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +90	°C
Soldering Temperature	T _{sol}	260 (for 10 sec)	°C
Electrostatic Discharge (HBM)	ESD	150	V
Power Dissipation	P _d	110	mW
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	45.0	---	90.0	mcd	I _F =5mA
Viewing Angle	2θ 1/2	---	130	---	deg	
Forward Voltage	V _F	2.70	---	3.10	V	
Reverse Current	I _R	---	---	50	μA	V _R =5V

Notes:

- 1.Tolerance of Luminous Intensity ±10%
- 2.Tolerance of Forward Voltage ±0.05V

Bin Range Of Luminous Intensity

Bin code	Min	Max	Unit	Condition
P1	45.0	57.0	mcd	I _F =5mA
P2	57.0	72.0		
Q1	72.0	90.0		

Bin Range Of Forward Voltage

Group	Bin	Min	Max	Unit	Condition
B5	29	2.70	2.80	V	IF=5mA
	30	2.80	2.90		
	31	2.90	3.00		
	32	3.00	3.10		

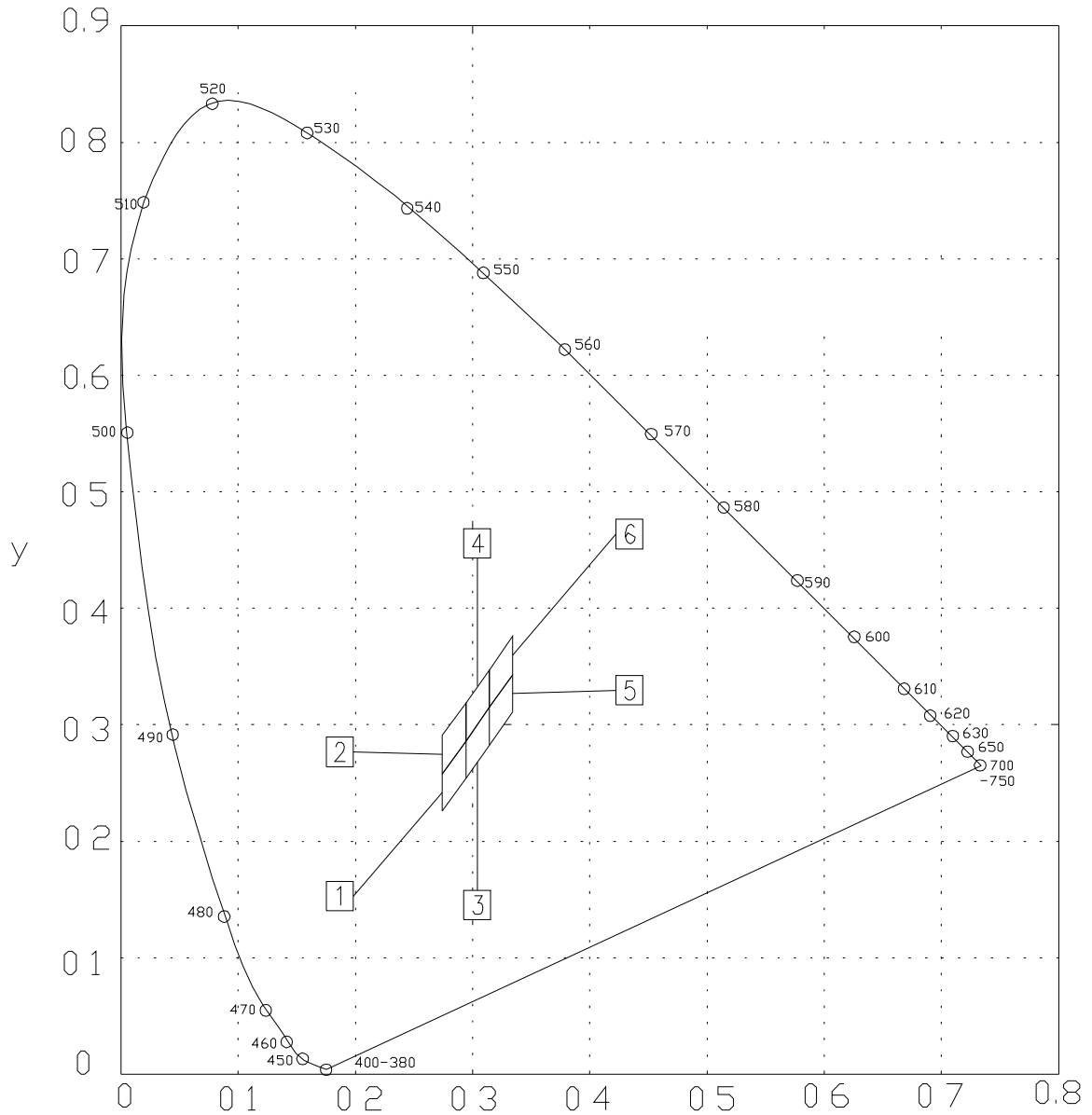
Chromaticity Coordinates Specifications for Bin Grading

Group	Bin Code	CIE -x	CIE-y	Condition
A	1	0.274	0.226	IF=5mA
		0.274	0.258	
		0.294	0.286	
		0.294	0.254	
	2	0.274	0.258	
		0.274	0.291	
		0.294	0.319	
		0.294	0.286	
	3	0.294	0.254	
		0.294	0.286	
		0.314	0.315	
		0.314	0.282	
	4	0.294	0.286	
		0.294	0.319	
		0.314	0.347	
		0.314	0.315	
	5	0.314	0.282	
		0.314	0.315	
		0.334	0.343	
		0.334	0.311	
	6	0.314	0.315	
		0.314	0.347	
		0.334	0.376	
		0.334	0.343	

Notes:

- 1.The C.I.E. 1931 chromaticity diagram (Tolerance ± 0.01).
- 2.The products are sensitive to static electricity and care must be fully taken when handling products.

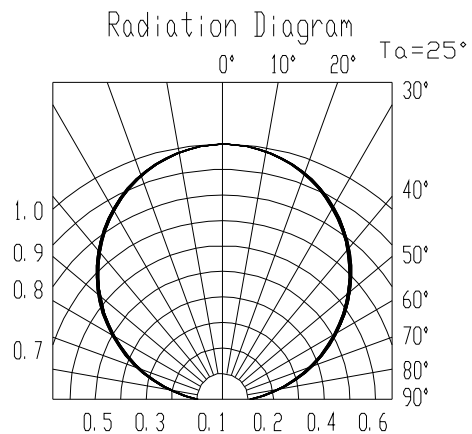
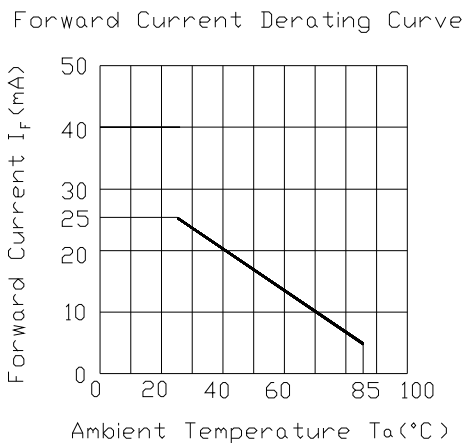
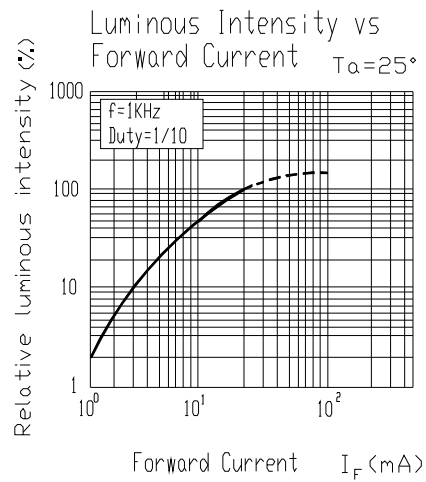
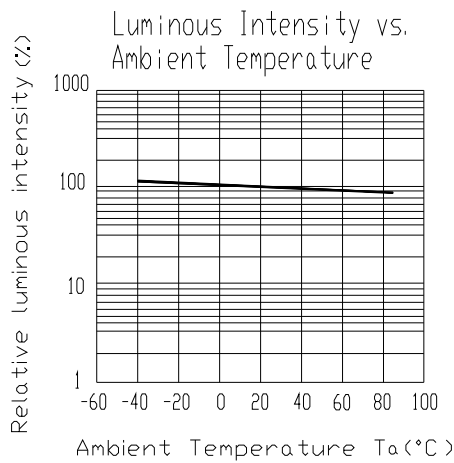
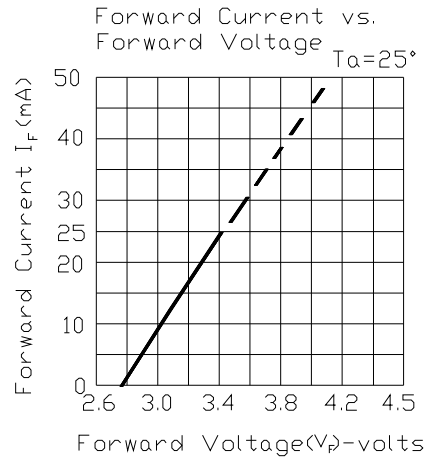
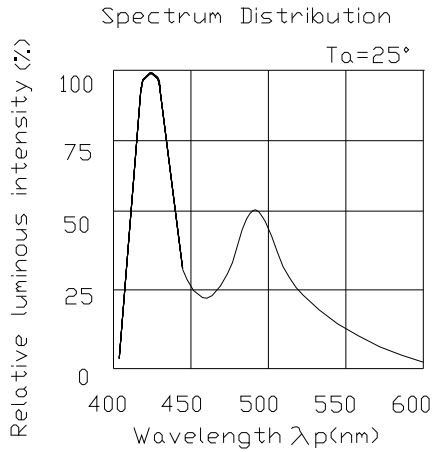




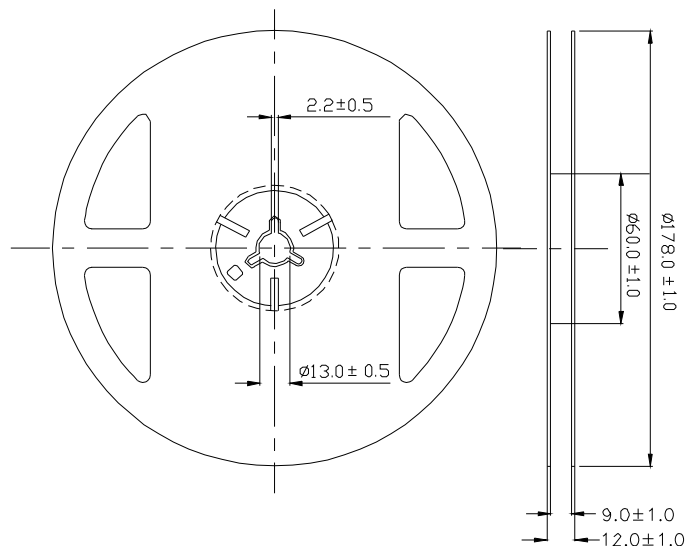
Specific binning requirements- please contact our home office



Typical Electro-Optical Characteristics Curves

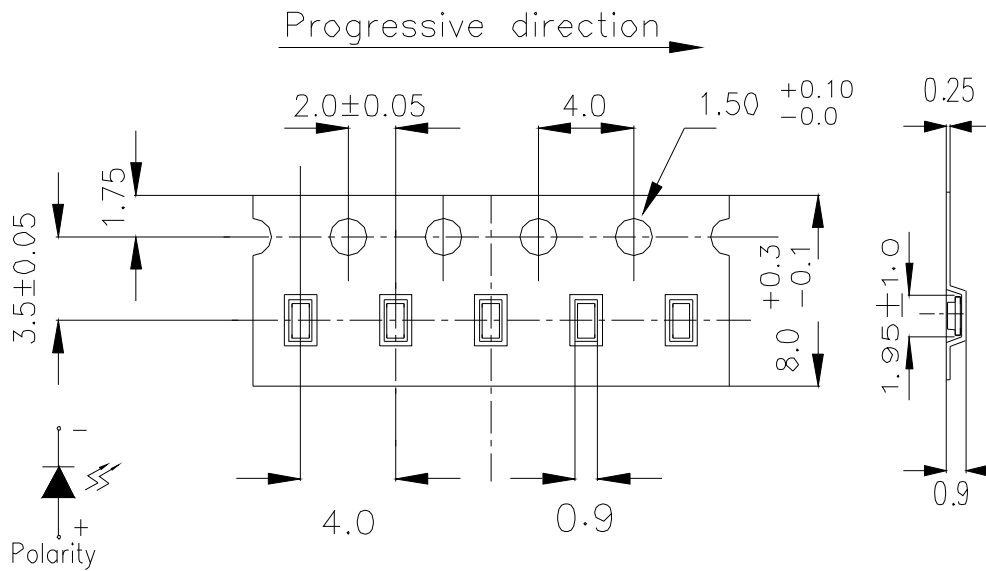


Reel Dimensions



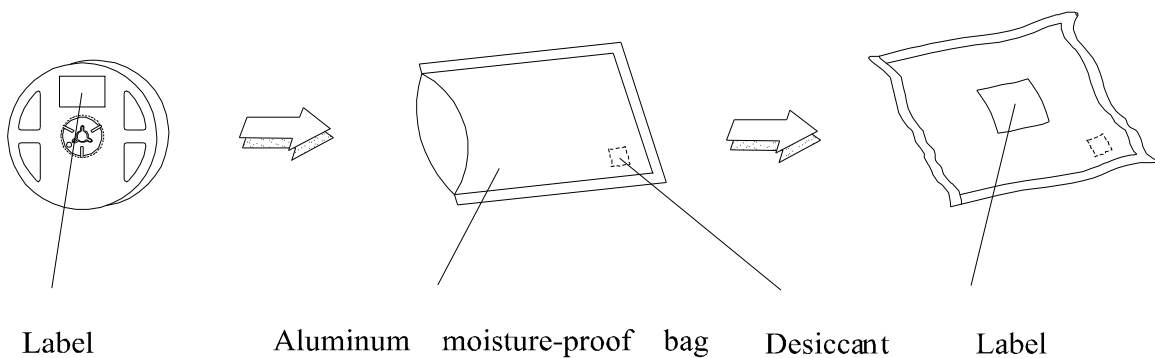
Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



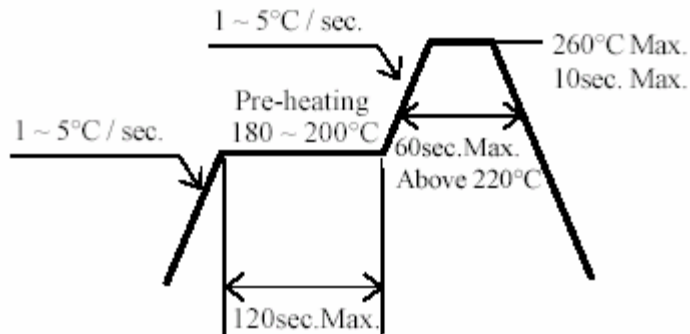
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Moisture Resistant Packaging



Soldering Condition

1. Pb-free solder temperature profile



2. Reflow soldering should not be done more than two times.
- 3 When soldering, do not put stress on the LEDs during heating.
- 4 After soldering, do not warp the circuit board.

Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.